



T-FORCE XTREEM DDR5 DESKTOP Memory

With T-FORCE LAB's superb R&D capability, the brand-new T-FORCE XTREEM DDR5 exceeds the frequency limit of DDR5 memory. The DDR5 high-performance memory module is successfully developed with our proprietary IC grading testing validation technology—GRADING METHOD FOR MEMORY (Invention patent number in Taiwan: I751093; Invention patent number in USA: US11488679B1). The product has T-FORCE logo symbolizing our utmost pride, showcasing its exceptional existence, it is definitely the best choice in the world of overclocking products. The product adopts 2mm aluminum alloy heat sink and thermal gap pad with high thermal conductivity, designed with meticulously layered high-quality aluminum sandblasted fins that are with black anodizing treatment, giving the surface a matte texture that is also anti-acid, alkaline, rust and inconducive, which all allow the product to have both a stylish look and perfect heat dissipation ability.

Primary functions and features

- Honorable T-FORCE Logo exceeds overclocking limits
- Meticulously layered high-quality aluminum sandblasted fin for exceptional heat dissipation
- Sturdy 2mm heat spreader for perfect heat dissipation improvement
- High-quality IC with the patented technique
- Power management chip for stable and effective power usage
- On-Die ECC for a more stable system
- Lifetime warranty

Main introduction

Honorable T-FORCE Logo exceeds overclocking limits

With T-FORCE LAB's superb R&D capability, the brand-new T-FORCE XTREEM DDR5 exceeds the frequency limit of DDR5 memory. The product has T-FORCE logo symbolizing our utmost pride, showcasing its exceptional existence, it is definitely the best choice in the world of overclocking products.

Meticulously layered high-quality aluminum sandblasted fins for exceptional heat dissipation

Inspired by the image of energy conversion between the hot and cold under high temperatures from a volcano, the exterior and looks of T-FORCE XTREEM DDR5 has meticulously layered high-quality aluminum sandblasted fins resembling the texture of basalt and the beach, delivering exceptional heat dissipation capabilities. The surface is etched with T-FORCE logo to certify its excellence.

Sturdy 2mm heat sink for perfect heat dissipation improvement

T-FORCE XTREEM DDR5 adopts 2mm aluminum alloy heat spreader to increase its quality and heat capacity. The product also has thermal gap pad with high thermal conductivity to strengthen PMIC heat dissipation effects, coupled with anti-acid, alkaline, rust and inconducive anodic treatment on the surface to deliver perfect heat dissipation performance overall.

High-quality IC with patented technique

Uses our proprietary IC grading testing validation technique—GRADING METHOD FOR MEMORY (Invention patent number in Taiwan: I751093; Invention patent number in USA: US11488679B1) to develop DDR5 high-performance memory module successfully.

Power management chip for stable and effective power usage

Power management chip minimizes noise interference, stabilizes power and distributes power to each electronic component effectively, supplying power to the system with stability and fastness.

On-Die ECC for a more stable system

Supported with On-die ECC providing error correction and detection, the mechanism stabilizes the system while pursuing performance.

Lifetime warranty

Comprehensive lifetime warranty is offered where exchanges free-of-charge for non-man-made damage are available under a simple and streamlined service.



Specifications

Module Type	DDR5 288 Pin ECC Registered DIMM					
Frequency	8200	8000	8000	7600	7600	7200
Capacity	2x24GB	2x16GB	2x24GB	2x24GB	2x16GB	2x16GB 2x24GB
Latency	CL38-49-49-84	CL38-48-48-84	CL38-49-49-84	CL36-47-47-84	CL36-45-45-84	CL34-42-42-84
Data Transfer Bandwidth	65,600 MB/s (PC5 65600)	64,000 MB/s (PC5 64000)	64,000 MB/s (PC5 64000)	60,800 MB/s (PC5 60800)	60,800 MB/s (PC5 60800)	57,600 MB/s (PC5 57600)
Voltage	1.4V	1.45V	1.4V	1.4V	1.4V	1.4V
Compatibility	INTEL 700 series					
Dimensions	48.8(H) x 134.5(L) x 8.2(W) mm					
Heat Spreader	Aluminum heat-spreader					
Profile	Intel XMP 3.0					
Warranty	Lifetime warranty					

Module Type	DDR5 288 Pin ECC Registered DIMM				
Frequency	6800	6800	6400	6000	6000
Capacity	2x24GB	2x16GB	2x16GB	2x16GB	2x16GB
Latency	CL34-42-42-84	CL34-44-44-84	CL32-39-39-84	CL38-38-38-78	CL30-36-36-76
Data Transfer Bandwidth	54,400 MB/s (PC5 54400)	54,400 MB/s (PC5 54400)	51,200 MB/s (PC5 51200)	48,000 MB/s (PC5 48000)	48,000 MB/s (PC5 48000)
Voltage	1.4V	1.4V	1.35V	1.25V	1.35V
Compatibility	INTEL 700 series				
Dimensions	48.8(H) x 134.5(L) x 8.2(W) mm				
Heat Spreader	Aluminum heat-spreader				
Profile	Intel XMP 3.0				
Warranty	Lifetime warranty				

※We reserve the right to modify product specifications without prior notice.

※Check "Product Compatibility Inquiry" before purchase for further info. <https://www.teamgroupinc.com/en/support/compatibility.php>

※Before purchasing memory products, please refer to the QVL(Qualified Vendor List) compatibility list first of the motherboard.

※The quality of the CPU memory controller (IMC) and the version from the BIOS of motherboard may both potentially affect the operating frequency of the memory.

※The overlocking memory with high frequency needs a more enhanced heat solution inside the case, to bring out better stability.

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※Do not mix memory modules of different capacities, frequencies, brands, or models. Each memory kit is paired through compatibility testing. Mixing different kits may cause system instability or failure to boot.

※Memory kits labeled "Support Intel XMP 3.0" only include XMP Profiles. Kits labeled "Support AMD EXPO" only include EXPO Profiles. Kits labeled "COMBINATION Intel XMP/AMD EXPO" include both XMP and EXPO Profiles.

※If the system fails to boot, reset the motherboard CMOS, enter BIOS with default frequency, and then enable the Profile to retry system boot.

※Failure to install and use the memory as per the official specifications, warnings, or operating instructions may result in the memory not operating at the speed indicated on the packaging, system instability, or damage to other hardware.

※For product-related or technical support issues, please contact our professional technical support team via email.



Ordering information

Color	Frequency	CAS Latency/Voltage	Capacity	IC Specifications	Team P/N
BLACK	DDR5-6000（PC5-48000）	CL30-36-36-76 1.35V	2x16GB	x8	FFXD532G6000HC30DC01
		CL38-38-38-78 1.25V	2x16GB	x8	FFXD532G6000HC38ADC01
	DDR5-6400（PC5-51200）	CL32-39-39-84 1.35V	2x16GB	x8	FFXD532G6400HC32ADC01
	DDR5-6800（PC5-54400）	CL34-44-44-84 1.4V	2x16GB	x8	FFXD532G6800HC34BDC01
		CL34-42-42-84 1.4V	2x24GB	x8	FFXD548G6800HC34ADC01
	DDR5-7200（PC5-57600）	CL34-42-42-84 1.4V	2x16GB	x8	FFXD532G7200HC34ADC01
			2x24GB	x8	FFXD548G7200HC34ADC01
	DDR5-7600（PC5-60800）	CL36-45-45-84 1.4V	2x16GB	x8	FFXD532G7600HC36FDC01
		CL36-47-47-84 1.4V	2x24GB	x8	FFXD548G7600HC36EDC01
	DDR5-8000（PC5-64000）	CL38-48-48-84 1.45V	2x16GB	x8	FFXD532G8000HC38DDC01
		CL38-49-49-84 1.4V	2x24GB	x8	FFXD548G8000HC38EDC01
	DDR5-8200（PC5-65600）	CL38-49-49-84 1.4V	2x24GB	x8	FFXD548G8200HC38EDC01

Color	Frequency	CAS Latency/Voltage	Capacity	IC Specifications	Team P/N
WHITE	DDR5-6000（PC5-48000）	CL30-36-36-76 1.35V	2x16GB	x8	FFWD532G6000HC30DC01
		CL38-38-38-78 1.25V	2x16GB	x8	FFWD532G6000HC38ADC01
	DDR5-6400（PC5-51200）	CL32-39-39-84 1.35V	2x16GB	x8	FFWD532G6400HC32ADC01
	DDR5-6800（PC5-54400）	CL34-44-44-84 1.4V	2x16GB	x8	FFWD532G6800HC34BDC01
		CL34-42-42-84 1.4V	2x24GB	x8	FFWD548G6800HC34ADC01
	DDR5-7200（PC5-57600）	CL34-42-42-84 1.4V	2x16GB	x8	FFWD532G7200HC34ADC01
			2x24GB	x8	FFWD548G7200HC34ADC01
	DDR5-7600（PC5-60800）	CL36-45-45-84 1.4V	2x16GB	x8	FFWD532G7600HC36FDC01
		CL36-47-47-84 1.4V	2x24GB	x8	FFWD548G7600HC36EDC01
	DDR5-8000（PC5-64000）	CL38-48-48-84 1.45V	2x16GB	x8	FFWD532G8000HC38DDC01
		CL38-49-49-84 1.4V	2x24GB	x8	FFWD548G8000HC38EDC01
	DDR5-8200（PC5-65600）	CL38-49-49-84 1.4V	2x24GB	x8	FFWD548G8200HC38EDC01

Color	Frequency	CAS Latency/Voltage	Capacity	IC Specifications	Team P/N
PINK	DDR5-6000 (PC5-48000)	CL30-36-36-76 1.35V	2x16GB	x8	FFPD532G6000HC30DC01
		CL38-38-38-78 1.25V	2x16GB	x8	FFPD532G6000HC38ADC01
	DDR5-6400 (PC5-51200)	CL32-39-39-84 1.35V	2x16GB	x8	FFPD532G6400HC32ADC01
	DDR5-6800 (PC5-54400)	CL34-44-44-84 1.4V	2x16GB	x8	FFPD532G6800HC34BDC01
		CL34-42-42-84 1.4V	2x24GB	x8	FFPD548G6800HC34ADC01
	DDR5-7200 (PC5-57600)	CL34-42-42-84 1.4V	2x16GB	x8	FFPD532G7200HC34ADC01
			2x24GB	x8	FFPD548G7200HC34ADC01
	DDR5-7600 (PC5-60800)	CL36-45-45-84 1.4V	2x16GB	x8	FFPD532G7600HC36FDC01
		CL36-47-47-84 1.4V	2x24GB	x8	FFPD548G7600HC36EDC01



T-FORCE is TEAM force. The red "T" on the logo of "TF" represents TEAMGROUP's passion for the storage products. The black "F" represents TEAMGROUP's over 18 years of promotion of storage products. The visual design of the perfect combination elegantly symbolizes a pair of flying wings.



PERFECT CHOICE

Products from Team Group Inc. have been well received by the technology media around the globe and have won honors such as COMPUTEX d&i awards, COMPUTEX Best Choice Award, GOOD DESIGN AWARD, Golden Pin Design Award, Taiwan Excellence Awards, iF Design Award and Red Dot Award.

GLOBALIZATION

Team Group Inc. has built up a strong center in Taiwan for production, R&D, sales and customer service, and has over 300 global sales agents and 400 employees worldwide. Team Group Inc. uses differentiating sales strategies with a global vision and localized channel management to establish a closed distribution network.

GUARANTEED QUALITY & WARRANTY SERVICE

Team Group Inc. is well praised by the industry and customers by adhering to the corporate philosophy of "Integrity, Innovation, Professionalism, Efficiency, Discipline, and Simplicity." We offer faster repair and exchange services than others, guaranteeing a minimized delivery time for every global customer.

SOLID R&D CAPABILITIES

With the best technical and manufacturing team, products from Team Group Inc. are made with innovation and strict quality control. Our memory technology has passed the ISO9001 and ISO14001 certifications, taking the lead in the memory industry with our latest overclocking memory modules.



3F., No.166, Jian 1st Rd., Zhonghe Dist., New Taipei City 23511, Taiwan
Team Group Inc.
Tel: +886-2-82265000 Fax: +886-2-82265808
mail: sales@teamgroup.com.tw / rma@teamgroup.com.tw

